

Serial No. 10/073,173

Attorney Docket No. 259/014

Request for Reconsideration dated July 21, 2004Reply to Office action mailed March 23, 2004**LISTING OF CLAIMS:**

1. (Original) A structure for providing resilient interconnections in a wafer level package, comprising a conductive pad that overlays an air space, wherein at least a portion of the air space extends laterally beyond the conductive pad.

2. (Original) The structure as claimed in claim 1, wherein the air space comprises a geometric structure having a plurality of perimeter interconnect support structures for the conductive pad.

3. (Original) The structure as claimed in claim 2, wherein at least one perimeter interconnect support structure also supports a conductive line electrically connected to the conductive pad.

4. (Original) The structure as claimed in claim 3, wherein the conductive line is a metal wire.

5. (Original) The structure as claimed in claim 1, wherein a major axis of the air space is radial to a center of the wafer level package.

6. (Original) The structure as claimed in claim 1, wherein a major axis of the air space is not radial to a center of the wafer level package.

7-20. (Cancelled).